

面板級

微波電漿光阻去除機

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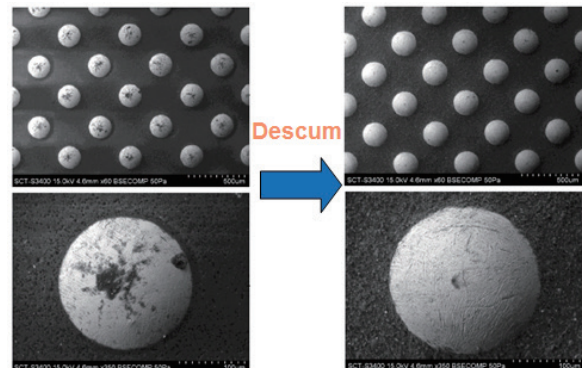
PLP Microwave Plasma Photoresist Removal Equipment

PRSM-BM2R6025A



機台特點 Characteristics

- 適用最大 600 x 600mm 面板尺寸
Applicable to panels up to 600 x 600 mm
- 大面積翹曲解決方案
Solution for large-area warpage.
- 系統搭配2個或更多製程腔
System supports two or more process chambers.
- 穩定的自動化傳輸系統
Stable automated transfer system.
- 全面數位控制系統，具備聯網功能
Fully digital control and SECS/GEM compliant.
- 3種製程模式選擇：微波、反應式離子蝕刻、微波+偏壓
Choice of 3 process mode : Microwave, RIE or Microwave+bias (dual source)
- 低損傷高密度微波電漿系統具備高效電漿處理效率
The low-damage, high-density microwave plasma system features high-efficiency plasma processing.
- 大面積微波源與中頻偏壓方案提升大面積均勻性
The large-area microwave source and medium frequency bias solutions enhance large-area uniformity.



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Leading in Thermal and UV Light Processing Equipment

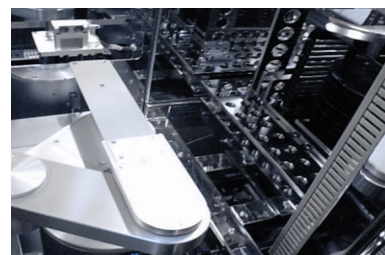
基板尺寸 Substrate size	300 x 300 mm / 510 x 515 mm / 600 x 600 mm
腔體數目 Number of chamber	2~4
傳送機構 Transfer system	4-axis dual arm robot
載入機構 Load port	2~4 FOUPs
電漿源 Plasma source	Microwave (2.45 GHz) RIE mode (bias, 2 MHz) Dual source (Microwave, bias)
電漿電源規格 Generator power	2.45 GHz, 6 kW (Microwave) 2 MHz, 2.5 kW (RIE / bias) 2.45 GHz, 10 kW (Microwave) 2 MHz, 5 kW (RIE / bias)
製程氣體 Process gas	O ₂ 、Ar、N ₂ 、CF ₄ 、N ₂ H ₂ 、ArH ₂ (Max. 7 gas lines)
氣體流量控制 Gas flow control	±1% of set point 註：流量設定≥全流量15%，控制精度為±1% of set point，<15%時控制精度為±0.15% of full scale Note: Control accuracy ±1% of set point when flow rate ≥15%, control accuracy ±0.15% of full scale when flow rate<15%
腔體材質 Material of chamber	Aluminum alloy
泵浦規格 Standard pump	Dry pump, pumping speed >1000 cfm @60 Hz
製程壓力計 Pressure gauge	Capacitive pressure sensor
製程壓力控制 EQ pressure	50~800 mTorr
控制系統 Control system	19.5 inch TFT panel / PC / Windows 10
載台溫度控制 Stage temperature controller	Thermo-chiller
規範 Compliance	SEMI S2-01, SEMI S8-01, SECS/GEM

Due to C SUN continuing efforts to improve their systems, these specifications are subject to change without notice.
受長期研發需要，本公司保有規格修改之權利，恕不另行通知

DM2024Q3-000-TW

應用 Applications

1. 面板級封裝應用
Penal level packaging applications
2. 光阻剝除
PR Stripping
3. 殘膠去除
Descum
4. 金屬表面氧化物去除
Removal of metal surface oxideslamination.
5. 氧化矽/氮化矽/矽蝕刻
SiO_x / SiN_x / Si etching
6. 聚合物去除
Polymer removal
7. 表面清潔及改質
Surface clean & treanment



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